

AD2000T/S

Fast, refined and innovative



TWIN Dicing concept with two opposing Spindles

World's smallest Dicing Machine.

Achieved smallest footprint possible utilizing our own core technology.

World's most efficient Dicing Machine

Delivering fast X-axis (Up to 1,000 mm/sec) and Y-axis (Up to 300 mm/sec) processing speed.
Low Cost of ownership.



Introducing refined Graphic User Interface

Tokyo Seimitsu was the first to Introduce TWIN Dicing Machine equipped with GUI and now refined GUI is available with HELP function as a standard feature for ease of operation.

Ease of maintenance

Widen front access door help improve routine maintenance with ease-of-maintenance in mind.

Tokyo Seimitsu has introduced Japan's first Wafer Dicing Machine, Model A-WA-75A in 1970 and tremendous contribution was made to success of Semiconductor industry with die separation process technology and its long term evolution with precession processing. Vast resource accumulated on Dicing Technology over four decades has enabled us to introduce next generation of Dicing machine, Model AD2000T with latest technology in FLUIDIC ENGINEERING, MECHATRONICS ENGINEERING and ENERGY CONSERVATION to lead the world with Dicing technology.

TOKYO SEIMITSU

Main Features

- 1** Optimized spacing by utilizing all components and optional unit well within the compartment
- 2** Standard Spindles up to 60,000 rpm
- 3** Enhanced throughput
 - 1: X axis 1,000 mm/sec, Y axis 300 mm/sec, and Z axis 80 mm/sec
 - 2: Two Optical Cutter-Set units
 - 3: The Worlds' smallest blade-to-blade distance
- 4** 17" LCD touch panel and new GUI (Graphical User Interface) with simple layout and large touch-buttons allow users' interactive operation



New GUI ▶
- 5** Easy and simple Kerf check function (AI kerf check function)
- 6** Over 10,000 recipes storable
- 7** USB port as standard (USB memory device can be used as external memory)
- 8** Ease-of-maintenance

Wide maintenance door and front-side accessibility allows easy of routine maintenance
- 9** Optimized vacuum controller

Reduces 50 % of air consumption compared with existing model

Specifications

Max. work size	φ 200 mm
Max. number of frames	8 inch
Spindle	Rotation 60,000 min-1 Max. blade diameter φ58 mm (2-Inch) Rated Output 1.8 KW
X axis	Available cutting range 260 mm Max. Speed 1000 mm/sec
Y1/Y2 axes	Available cutting range 260 mm Max. Speed 300 mm/sec Resolution 0.078 µm Accuracy 0.002 mm / 210 mm
Z1/Z2 axes	Stroke 34 mm Resolution 0.002 µm Max. Speed 80 mm/sec Repeatability 0.001 mm
θ axis	Range of rotation 380°
Misc	Voltage 3 Phase AC200 to 220V ±10 % (Transformer adoptable) Power consumption 6.0kVA (MAX) Air pressure 0.55 to 0.7 MPa Avg. Air consumption 210 L/ min (0.55 MPa) Cutting Water, and others (pressure) 0.3 to 0.5 MPa Cutting Water, and others (Max Flow) Cutting Water:10.0 L/min Others:3.6 L/min Cooling Water (pressure) 0.3 to 0.5 MPa Cooling Water (Max Flow) 3.4 L/min (0.3 MPa) Exhaust 5.0 m³/ min more Size (W*D*H) 1080 mmX1190 mmX1900 mm Weight 1100 kg

Notes) *Specifications of the Consumption, Cutting water and Cooling water are for AD2000T.

*All specifications above may be changed without notice.

**Maintenance**

The large door and processing space increased the maintainability.

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